

AMENDMENTS TO THE CLAIMS

a3
1. (currently amended) An electronic connector, comprising:
a heat generating electronic component ~~capable of electronically coupling~~
~~two data devices together~~; and

a housing ~~positioned about~~ surrounding and touching said heat generating electronic component; said housing being made of a thermally conductive material; said thermally conductive material being a net-shape injection moldable polymer composition with a base matrix of liquid crystal polymer material loaded with thermally conductive filler and having a thermal conductivity of at least 30 W/m²K; said housing being in thermal communication with said heat generating electronic component with heat ~~being~~ dissipating from said heat generating electronic component and through said housing.

2. (canceled) }

3. (canceled) }

4. (original) The electronic connector of Claim 1, wherein said heat generating electronic component is a semiconductor device.

5. (original) The electronic connector of Claim 1, wherein said heat generating electronic component is a laser.

6. (original) The electronic connector of Claim 1, wherein said electronic connector is an opto-electronic connector interface between fiber optic cable and electronic cable.

7. (canceled) }

8. (currently amended) The electronic connector of Claim 7 1, wherein said thermally conductive filler is selected from the group consisting of carbon fiber, aluminum, copper, boron nitride, alumina, magnesium and brass.

9. (canceled)

10. (canceled)

11. (currently amended) A method of forming an electronic connector, comprising the steps of:

a3 providing a heat generating electronic component ~~capable of electronically coupling two data devices together~~ having a first port and a second port;

~~molding~~ overmolding an outer housing of injection moldable thermally conductive polymer material, with a base matrix of liquid crystal polymer with filler therein, around said heat generating electronic component leaving said first port and said second port of said heat generating electronic component exposed.

12. (canceled)

13. (currently amended) The method of Claim ~~12~~ 11, wherein said ~~thermally conductive~~ filler is thermally conductive and selected from the group consisting of carbon fiber, aluminum, copper, boron nitride, alumina, magnesium, nickel and brass.

14. (canceled)

15. (currently amended) The method of Claim ~~14~~ 11, wherein said ~~electromagnetically shielding~~ filler material shields electromagnetic waves and is ~~metallic~~ filler selected from the group consisting of aluminum, copper, alumina, magnesium and brass.

16. (canceled)